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FDS8928A

Dual N & P-Channel Enhancement Mode Field Effect Transistor

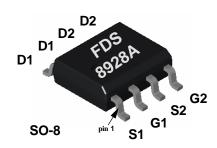
General Description

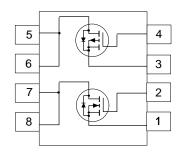
These dual N- and P -Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as notebook computer power management and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- High density cell design for extremely low R_{DS(ON)}.
- High power and current handling capability in a widely used surface mount package.
- Dual (N & P-Channel) MOSFET in surface mount package.







Absolute Maximum Ratings T₄ = 25°C unless otherwise noted

Symbol	Parameter		N-Channel	P-Channel	Units	
V _{DSS}	Drain-Source Voltage		30	-20	V	
V _{GSS}	Gate-Source Voltage		8	-8	V	
I _D	Drain Current - Continuous	(Note 1a)	5.5	-4	А	
	- Pulsed		20	-20		
P _D	Power Dissipation for Dual Operation		2	W		
	Power Dissipation for Single Operation	(Note 1a)	1.6			
		(Note 1b)	1	1		
		(Note 1c)	0.	.9		
T _J ,T _{STG}	Operating and Storage Temperature Range		-55 to	°C		
THERMA	L CHARACTERISTICS		•			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)		7	78		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1) 40		°C/W		

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Units
OFF CHAR	ACTERISTICS		•		,	•	•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{gs} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	N-Ch	30			V
		$V_{gs} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	P-Ch	-20			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C	N-Ch		32		mV/°C
		$I_D = -250 \mu\text{A}$, Referenced to 25 °C	P-Ch		-23		
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, \ V_{GS} = 0 \text{ V}$	N-Ch			1	μΑ
		$V_{DS} = -16 \text{ V}, \ V_{GS} = 0 \text{ V}$	P-Ch			-1	μA
I _{GSSF}	Gate - Body Leakage, Forward	$V_{gs} = 8 \text{ V}, V_{DS} = 0 \text{ V}$	All			100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	$V_{gs} = -8 \text{ V}, V_{DS} = 0 \text{ V}$	All			-100	nA
ON CHARA	CTERISTICS (Note 2)						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	N-Ch	0.4	0.67	1	V
		$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	P-Ch	-0.4	-0.6	-1	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C	N-Ch		-3		mV/°C
		I _D =-250 μA, Referenced to 25 °C	P-Ch		4		
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{gs} = 4.5 \text{ V}, I_{D} = 5.5 \text{ A}$	N-Ch		0.025	0.03	Ω
		$V_{gs} = 2.5 \text{ V}, I_{D} = 4.5 \text{ A}$			0.031	0.038	
		$V_{gs} = -4.5 \text{ V}, I_{D} = -4 \text{ A}$	P-Ch		0.043	0.055	
		$V_{gs} = -2.5 \text{ V}, I_{D} = -3.4 \text{ A}$			0.059	0.072	
I _{D(on)}	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$	N-Ch	20			Α
		$V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$	P-Ch	-20			
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 5.5 \text{ A}$	N-Ch		20		S
		$V_{DS} = -5 \text{ V}, \ I_{D} = -4 \text{ A}$	P-Ch		13		S
DYNAMIC (CHARACTERISTICS						
C _{iss}	Input Capacitance	$\begin{split} V_{DS} = 10 \text{ V}, & V_{GS} = 0 \text{ V}, \\ f = 1.0 \text{ MHz} & \\ \hline \text{P-Ch} \end{split}$	N-Ch		900		pF
			P-Ch		1130		
C _{oss}	Input Capacitance		N-Ch		410		pF
		$V_{DS} = -10 \text{ V}, \ V_{GS} = 0 \text{ V},$	P-Ch		480		
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz	N-Ch		110		pF
			P-Ch		120	_	

Electrical Characteristics (continued)

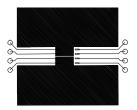
SWITCHING CHARACTERISTICS (Note 2)

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Units
t _{D(on)}	Turn - On Delay Time	$V_{DS} = 6 V, I_{D} = 1 A$	N-Ch		6	12	ns
		$V_{GS} = 4.5 \text{ V}$, $R_{GEN} = 6 \Omega$	P-Ch		8	16	
t,	Turn - On Rise Time		N-Ch		19	31	ns
			P-Ch		23	37	
t _{D(off)}	Turn - Off Delay Time	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ A}$	N-Ch		42	67	ns
		$V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$	P-Ch		260	360	
t,	Turn - Off Fall Time		N-Ch		13	24	ns
			P-Ch		90	125	
Q _q	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_{D} = 5.5 \text{ A},$	N-Ch		19.8	28	nC
		$V_{GS} = 4.5 \text{ V}$	P-Ch		20	28	
Q_{gs}	Gate-Source Charge		N-Ch		2		nC
		$V_{DS} = -5 \text{ V}, I_{D} = -4 \text{ A},$	P-Ch		2.8		
Q_{gd}	Gate-Drain Charge	V _{GS} = -5 V	N-Ch		6.3		nC
			P-Ch		3.2		
DRAIN-SO	URCE DIODE CHARACTERISTICS AND	MAXIMUM RATINGS					
I _s	Maximum Continuous Drain-Source Diode Forward Current		N-Ch			1.3	Α
			P-Ch			-1.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{cs} = 0 \text{ V}, I_{s} = 1.3 \text{ A} \text{ (Note 2)}$	N-Ch		0.68	1.2	V

Notes:

1. R_{BA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BA} is guaranteed by design while $\boldsymbol{R}_{\text{\tiny BCA}}$ is determined by the user's board design.

 $V_{gs} = 0 \text{ V}, I_{s} = -1.3 \text{ A} \text{ (Note 2)}$



a. 78°C/W on a 0.5 in² pad of 2oz copper.





P-Ch

-1.2

V

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%..

Typical Electrical Characteristics: N-Channel

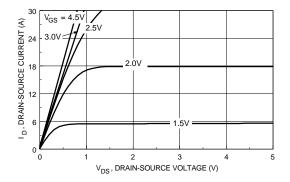


Figure 1. On-Region Characteristics.

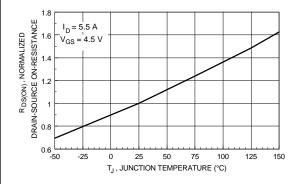


Figure 3. On-Resistance Variation with Temperature.

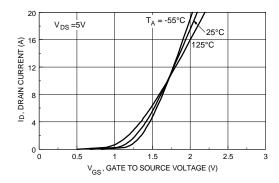


Figure 5. Transfer Characteristics.

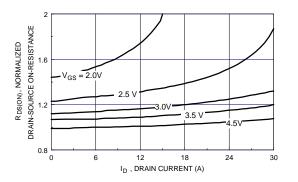


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

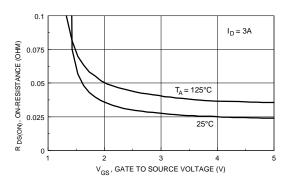


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

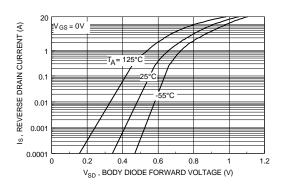


Figure 6. Body Diode Forward Voltage
Variation with Source Current
and Temperature.

Typical Electrical Characteristics: N-Channel (continued)

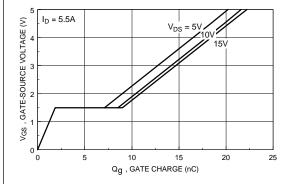


Figure 7. Gate Charge Characteristics.

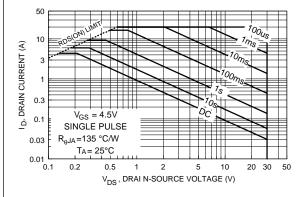


Figure 9. Maximum Safe Operating Area.

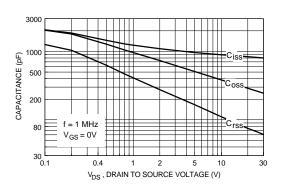


Figure 8. Capacitance Characteristics.

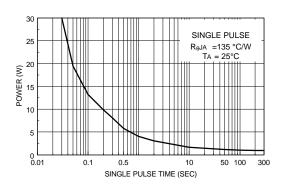


Figure 10. Single Pulse Maximum Power Dissipation.

Typical Electrical Characteristics: P-Channel

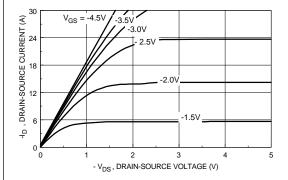


Figure 11. On-Region Characteristics.

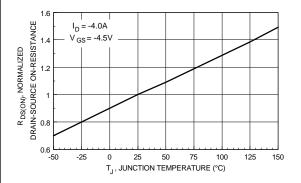


Figure 13. On-Resistance Variation with Temperature.

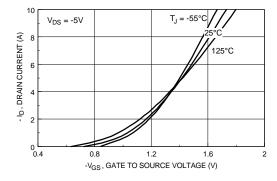


Figure 15. Transfer Characteristics.

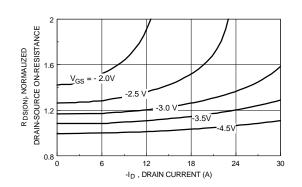


Figure 12. On-Resistance Variation with Drain Current and Gate Voltage.

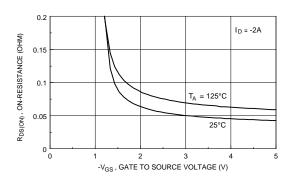


Figure 14. On-Resistance Variation with Gate-to-Source Voltage.

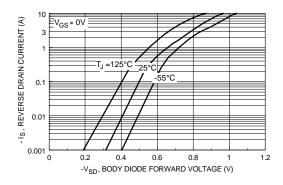


Figure 16. Body Diode Forward Voltage
Variation with Source Current
and Temperature.

Typical Electrical Characteristics: P-Channel (continued)

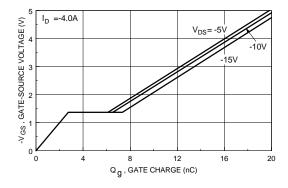


Figure 17. Gate Charge Characteristics.

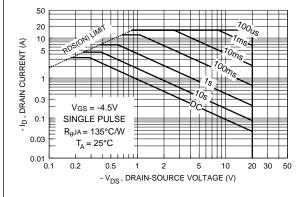


Figure 19. Maximum Safe Operating Area.

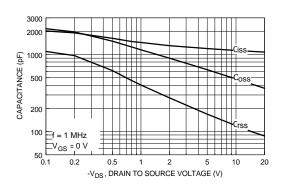


Figure 18. Capacitance Characteristics.

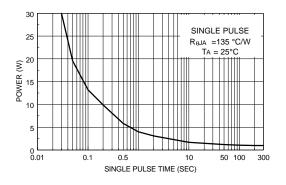


Figure 20. Single Pulse Maximum Power Dissipation.

Typical Thermal Characteristics: N & P-Channel (continued)

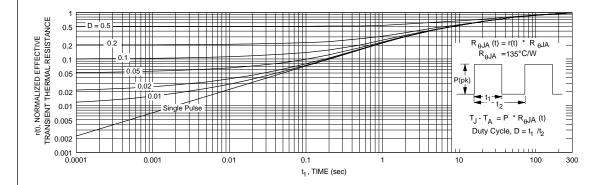


Figure 21. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in note 1.

Transient thermalresponse will change depending on the circuit board design.

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